

L Number	Hits	Search Text	DB	Time stamp
2	1350	(257/777).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 16:54
3	2613	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 16:55
4	4196	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 17:12
5	1743	257/779	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 17:30
6	2057	257/780	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 17:45
7	1063	257/781	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 18:03
8	4196	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 18:01
9	3831	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 18:12
10	1		USPAT	2004/10/27 18:06
11	1		USPAT	2004/10/27 18:07
12	1		USPAT	2004/10/27 18:07
13	2661	257/724	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 18:30
14	1209	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 18:47
15	2825	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 19:06
16	2768	257/690	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 19:23
17	3612	(semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)	USPAT	2004/10/27 22:23
18	487	((semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)) and (ball or bump) with (big or large)	USPAT	2004/10/27 22:24

19	2749	257/700	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 20:00
20	2211	438/108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 20:25
21	37	"5844315"	USPAT	2004/10/27 20:12
22	1		USPAT	2004/10/27 20:09
23	1		USPAT	2004/10/27 20:09
24	1		USPAT	2004/10/27 20:09
25	1		USPAT	2004/10/27 20:09
26	1		USPAT	2004/10/27 20:09
27	1		USPAT	2004/10/27 20:09
28	1		USPAT	2004/10/27 20:09
29	1		USPAT	2004/10/27 20:10
30	1		USPAT	2004/10/27 20:11
31	1		USPAT	2004/10/27 20:11
32	35	"5608265"	USPAT	2004/10/27 20:12
33	1045	438/109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 20:42
34	3850	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 21:34
37	0	stack\$3 near (semiconductor or chip or die) and (lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor.	USPAT	2004/10/27 21:40
38	0	(lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor.	USPAT	2004/10/27 21:36
39	0	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) near memory and (semiconductor or chip or die) near microprocessor.	USPAT	2004/10/27 21:37
40	0	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor.	USPAT	2004/10/27 21:39
41	0	257/777 and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor.	USPAT	2004/10/27 21:37
42	0	(semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor.	USPAT	2004/10/27 21:37
43	0	(semiconductor or chip or die) with memor\$3 and (semiconductor or chip or die) with micro near processor.	USPAT	2004/10/27 21:38
44	0	(semiconductor or chip or die or IC) with memor\$3 and (semiconductor or chip or die or IC) with microprocessor.	USPAT	2004/10/27 21:39
45	91434	(semiconductor or chip or die or IC) with memor\$3	USPAT	2004/10/27 21:38
46	0	(semiconductor or chip or die or IC) with microprocessor.	USPAT	2004/10/27 21:39
47	0	(semiconductor or chip or die or IC) with micro near processor.	USPAT	2004/10/27 21:39
48	0	(semiconductor or chip or die or IC) with micro-processor.	USPAT	2004/10/27 21:39
49	22456	(semiconductor or chip or die or IC) with microprocessor	USPAT	2004/10/27 21:39

50	188	stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor	USPAT	2004/10/27 21:40
51	0	stack\$3 near (semiconductor or chip or die) and (lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor	USPAT	2004/10/27 21:40
52	5	(lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor	USPAT	2004/10/27 22:45
54	0	((semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)) and (ball or bump) with (big or large)	JPO	2004/10/27 22:24
53	104	(semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)	JPO	2004/10/27 22:24
55	5	((lower or bottom) near (semiconductor or chip or die) with memory and (upper or top) near (semiconductor or chip or die) with microprocessor) and (semiconductor or chip or die) with memory and (semiconductor or chip or die) with microprocessor	USPAT	2004/10/27 22:46